



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #16758Generic Copy

Issue Date: 09-Nov-2011

TITLE: Qualification of ON Semiconductor's Seremban Site as the die sales assembly site for CREE's wafer sales devices.

PROPOSED FIRST SHIP DATE: 09-Mar-2012 or earlier with customer approval

AFFECTED CHANGE CATEGORY(S): Die Sales assembly site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Swei Huey Wong <sueihuey.wong@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

ON Semiconductor is notifying customer of its plan to qualify production (saw, inspection & packaging) of wafer sales products in ON Semiconductor's Seremban facility.

A qualification plan has been selected to ensure wafer quality and packaging specifications are met. No changes to wafer fab source, packaging & device electrical performance as a result of this die sales assembly site qualification.

QUALIFICATION PLAN:

Estimated Date for Qualification Completion: 11/30/2011.
Samples should be available after completion of Qualification.

List of affected General Parts:

HBL21000RP

List of Customer Specific Parts

FCDN605-TKY

FCDN608-TKY